Surface Mount Schottky Power Rectifier

SMA Power Surface Mount Package

This device employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State of the art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bent Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Guardring for Stress Protection
- NRVBA & SBRA Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 70 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 12 mm tape, 5000 units per 13 inch reel
- Polarity: Cathode Lead Indicated by Either Notch in Plastic Body or Polarity Band



ON Semiconductor®

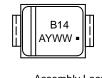
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SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES 40 VOLTS



SMA CASE 403D

MARKING DIAGRAM



= Assembly Location = Year

= Work Week

А

Y

WW

= Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRA140T3G	SMA (Pb-Free)	5,000 / Tape & Reel
NRVBA140T3G	SMA (Pb–Free)	5,000 / Tape & Reel
NRVBA140T3G-VF01	SMA (Pb–Free)	5,000 / Tape & Reel
SBRA140T3G-VF01	SMA (Pb–Free)	5,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
Average Rectified Forward Current (At Rated V _R , $T_C = 95^{\circ}C$)	Ι _Ο	1.0	A
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _C = 100°C)	I _{FRM}	2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	30	A
Storage Temperature	T _{stg}	-55 to +150	°C
Operating Junction Temperature	TJ	-55 to +125	°C
Voltage Rate of Change (Rated V _R , T _J = 25°C)	dv/dt	10,000	V/µs
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

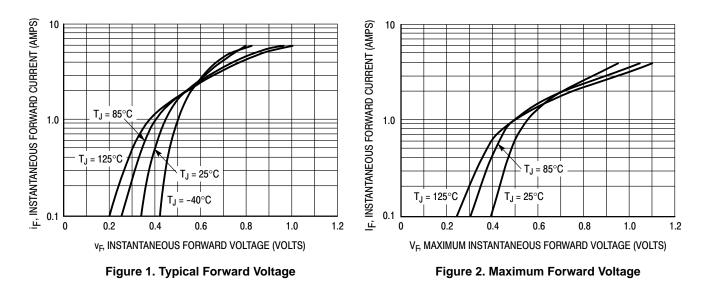
Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 1)	R _{θJL}	35	°C/W
Thermal Resistance, Junction-to-Ambient (Note 1)	R _{θJA}	86	

1. Mounted on 2" Square PC Board with 1" Square Total Pad Size, PC Board FR4.

ELECTRICAL CHARACTERISTICS

Characteristic		Symbol	Va	lue	Unit
Maximum Instantaneous Forward Voltage (Note 2)		V _F	T _J = 25°C	T _J = 100°C	V
(I _F :	(I _F = 1.0 A) (I _F = 2.0 A)		0.55 0.71	0.505 0.74	
Maximum Instantaneous Reverse Current $(V_R = 4)$ see Figure 4 for other Values $(V_R = 4)$		I _R	$T_J = 25^{\circ}C$	T _J = 100°C	mA
	(V _R = 40 V) (V _R = 20 V)		0.5 0.1	10 4.0	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width \leq 250 µs, Duty Cycle \leq 2.0%.



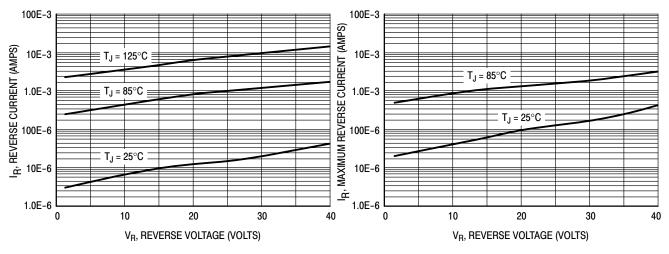
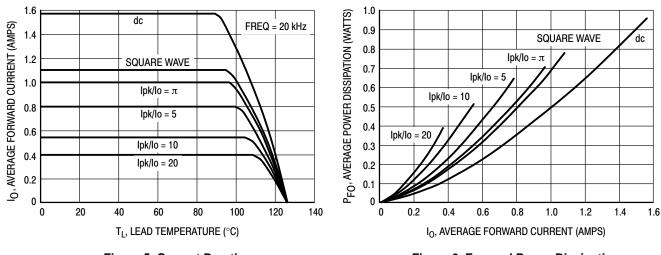


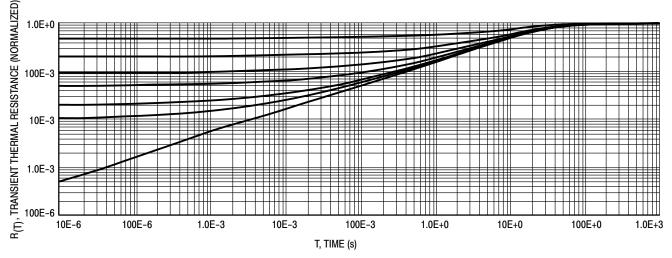
Figure 3. Typical Reverse Current

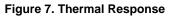
Figure 4. Maximum Reverse Current











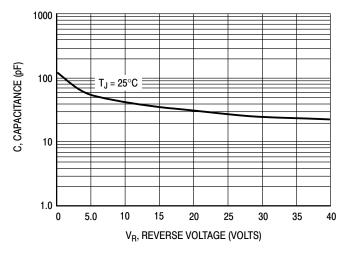
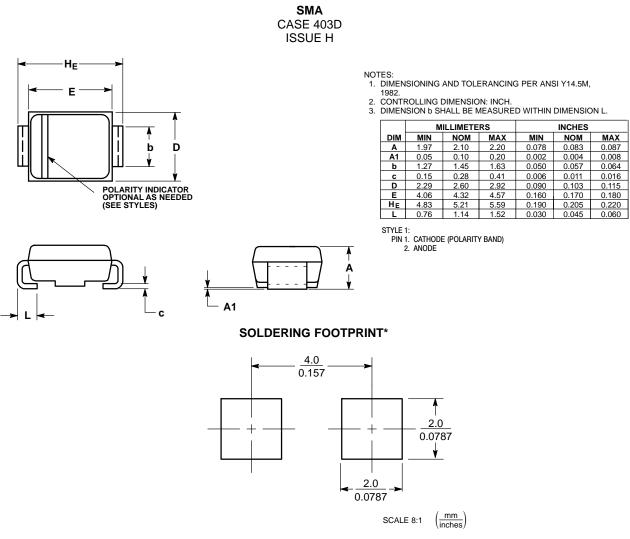


Figure 8. Capacitance

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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